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Product Change Notification

PCN Publish Date: 08/04/2010

PCN#: 360

Change Title: Recommended Solder Pad Layout Change

Products Affected:

Model Number	Part Number
NC26SMLF	509LF-0.032768-xxxxx

Description of Change to the Customer: Remove solder pad for can from recommended solder pad layout. Can should not be soldered to the circuit board or grounded. If securing the can to the board is desired, a rubber adhesive is recommended.

Reason for Change: Excessive heat necessary to solder the crystal can may damage the crystal.

Schedule of Change: Change is effective immediately.

Customer Impact and Response: We sincerely hope this change will have minimal impact on our customers. If you have any questions, please contact Fox Technical Support at www.foxonline.com/email.htm or call 239-693-0099.

NC26SMLF OLD AND NEW SOLDER PAD LAYOUT

OLD

NEW

